



Tin Whisker Workshop

May 29, 2007

Agenda

8:00 am	Introduction	Carol Handwerker, Purdue University, Workshop Moderator
8:15 am	The Effect of Temperature and Humidity Variations on Whisker Growth: Results of iNEMI Environmental Testing	Heidi Reynolds, Sun Microsystems
9:00 am	Pitfalls in Physical Measurements of Tin Whiskers	John Osenbach, Agere Systems
9:15 am	Correlation between Whisker Initiation and Compressive Stress in Electrodeposited SnCu Coating on Cu leadframe	Takahiko Kato, Hitachi
10:00 am	Break	
10:20 am	Bright Sn and SnCu Electrodeposits on Substrates Not Forming Interfacial Intermetallic Compounds: Observation of Hillock and Whisker Growth and Stress Measurements by Beam Deflection Method	Maureen Williams, NIST
11:00 am	Matte Sn Electroplating in Mass Production and Testing According to JESD201	P. Oberndorf, NPX Semiconductor
11:30 am	Metallurgical Considerations	Carol Handwerker, Purdue University
12:00 pm	Lunch	
1:15 pm	X-ray Measurement of Stress in Sn Electrodeposits	Maureen Williams, NIST and Robert Hilty, Tyco
1:45 pm	Quantifying Compressive Stress Contributions to Whisker Growth	Robert Hilty, Tyco
2:15 pm	Understanding Tin Whiskers	George Galyon, IBM
3:00 pm	Tin Whisker Mitigation - User Perspective	Joe Smetana, Alcatel-Lucent
3:30 pm	Evaluation of Conformal Coatings as a Tin Whisker Mitigation Strategy, Part II	Thomas Woodrow, Boeing
4:00 pm	Breakout Sessions – Open Discussion	
5:30 pm	Adjourn	